

IN THE CLAIMS

1-5. (Cancelled)

6. (Currently Amended) A solid-state complementary metal-oxide semiconductor type image pickup device, comprising:

a semiconductor substrate having a well region formed thereon; and

a pixel unit comprising a plurality of pixels on the semiconductor substrate, each pixel in the pixel unit including

(a) a photoelectric conversion element formed in said well region for receiving light and producing signal charge in accordance with an amount of the received light;

(b) a readout section formed in said well region for reading out the signal charge produced by said photoelectric conversion element at a predetermined readout timing;

(c) a node connecting the photo electric conversion element through the readout section ; and

(d) voltage control means- unit for applying a predetermined substrate bias voltage to said well region upon reading out of the signal charge by said readout section.

7. (Currently Amended) The complementary metal-oxide semiconductor type solid-state image pickup device according to claim 6, wherein said photoelectric conversion element is provided for each of a plurality of pixels formed are arranged in a two-dimensional array on said semiconductor substrate.

8. (Currently Amended) The complementary metal-oxide semiconductor type solid-state image pickup device according to claim 7, wherein said well region is formed electrically integrally integral in a region of said semiconductor substrate which includes all

of said pixels arranged in the two-dimensional array, and a common substrate bias voltage to all of said pixels is applied to the well regions.

9. (Currently Amended) The complementary metal-oxide semiconductor type solid-state image pickup device according to claim 7, wherein said well region is formed in an electrically isolated relationship for each row of said pixels arranged in the two-dimensional array, and an independent substrate bias voltage is applied to the cell regions for each row.

10. (Currently Amended) The complementary metal-oxide semiconductor type solid-state image pickup device according to claim 6, wherein said well region is a p-type well region and the substrate bias voltage is a negative voltage.

11. (Currently Amended) The complementary metal-oxide semiconductor type solid-state image pickup device according to claim 6, wherein said solid-state image pickup device is a complementary metal-oxide semiconductor type solid state image pickup device which includes a plurality of pixels each of each pixel which also includes said photoelectric conversion element and a pixel transistor for converting the signal charge read out from said photoelectric conversion element into an electric signal and outputting the electric signal to a signal line.

12. (Cancelled) .

13. (Currently Amended) A complementary metal-oxide semiconductor type solid-state image pickup device, comprising:

a semiconductor substrate having a well region formed thereon; and  
a pixel unit comprising a plurality of pixels on the semiconductor substrate, each pixel in the pixel unit including

(a) a photoelectric conversion element formed in said well region for receiving light and producing signal charge in accordance with an amount of the received light;

(b) a readout section formed in said well region for reading out the signal charge produced by said photoelectric conversion element at a predetermined readout timing; and

(c) a node connecting the photo electric conversion element through the readout section, and

(d) voltage control means for applying a substrate bias voltage to said well region and changing the substrate bias voltage during a storage period of the signal charge by said photoelectric conversion element.

14. (Currently Amended) The complementary metal-oxide semiconductor type solid-state image pickup device according to claim 13, wherein said photoelectric conversion element is provided for each of a plurality of pixels formed are in a two-dimensional array on said semiconductor substrate.

15. (Currently Amended) The complementary metal-oxide semiconductor type solid-state image pickup device according to claim 14, wherein said well region is formed electrically integrally in a region of said semiconductor substrate which includes all of said pixels arranged in the two-dimensional array, and a common substrate bias voltage to all of said pixels is applied to the well regions.

16. (Currently Amended) The complementary metal-oxide semiconductor type solid-state image pickup device according to claim 14, wherein said well region is formed in an electrically isolated relationship for each row of said pixels arranged in the two-dimensional array, and an independent substrate bias voltage is applied to the cell regions for each row.

17. (Currently Amended) The complementary metal-oxide semiconductor type solid-state image pickup device according to claim 13, wherein said well region is a p-type well region and the substrate bias voltage is a negative voltage.

18. (Currently Amended) The complementary metal-oxide semiconductor type solid-state image pickup device according to claim 13, wherein said solid state image pickup

device is a complementary metal oxide semiconductor type solid state image pickup device which includes a each of said plurality of pixels each of which also includes said photoelectric conversion element and a pixel transistor for converting the signal charge read out from said photoelectric conversion element into an electric signal and outputting the electric signal to a signal line.

19. (Cancelled)

20. (Currently Amended) A driving-method for driving a solid-state image pickup device comprising

- (a) a semiconductor substrate having a well region formed thereon; and
- (b) a pixel unit comprising a plurality of pixels on the semiconductor substrate, each pixel in the pixel unit including
  - (i) a photoelectric conversion element formed in said well region for receiving light and producing signal charge in accordance with an amount of the received light;
  - (ii) a readout section formed in said well region for reading out the signal charge produced by said photoelectric conversion element at a predetermined readout timing;
  - (iii) a node connecting the photo electric conversion element through the readout section, and
  - (iv) voltage control means for applying a substrate bias voltage to said well region and changing the substrate bias voltage during a storage period of the signal charge by said photoelectric conversion element,

wherein a photoelectric conversion element for receiving light and producing signal charge in accordance with an amount of the received light and a readout section for reading out the signal charge produced by said photoelectric conversion element at a predetermined readout timing are provided in a well region formed on a semiconductor substrate,

said method comprising the steps of:

converting light to a signal charge;

storing said signal charge during a charge storage period; and

a step of applying a predetermined substrate bias voltage to said well region upon reading out of the signal charge by said readout section during said readout period.

21. (Currently Amended) The driving method for a complementary metal-oxide semiconductor type solid-state image pickup device according to claim 20, wherein said photoelectric conversion element is provided for each of a plurality of pixels formed in a two-dimensional array on said semiconductor substrate.

22. (Currently Amended) The driving method for complementary metal-oxide semiconductor type a solid-state image pickup device according to claim 21, wherein said well region is formed electrically integrally in a region of said semiconductor substrate which includes all of said pixels arranged in the two-dimensional array, and a common substrate bias voltage to all of said pixels is applied to the well regions.

23. (Currently Amended) The driving method for a complementary metal-oxide semiconductor type solid-state image pickup device according to claim 21, wherein said well region is formed in an electrically isolated relationship for each row of said pixels arranged in the two-dimensional array, and an independent substrate bias voltage is applied to the cell regions for each row.

24. (Currently Amended) The driving method for a complementary metal-oxide semiconductor type solid-state image pickup device according to claim 20, wherein said well region is a p-type well region and the substrate bias voltage is a negative voltage.

25. (Currently Amended) A driving method for driving for a complementary metal-oxide semiconductor type solid-state image pickup device comprising

(a) a semiconductor substrate having a well region formed thereon; and

(b) a pixel unit comprising a plurality of pixels on the semiconductor substrate, each pixel in the pixel unit including

- (i) a photoelectric conversion element formed in said well region for receiving light and producing signal charge in accordance with an amount of the received light;
- (ii) a readout section formed in said well region for reading out the signal charge produced by said photoelectric conversion element at a predetermined readout timing;
- (iii) a node connecting the photo electric conversion element through the readout section, and
- (iv) voltage control means for applying a substrate bias voltage to said well region and changing the substrate bias voltage during a storage period of the signal charge by said photoelectric conversion element,

wherein a photoelectric conversion element for receiving light and producing signal charge in accordance with an amount of the received light and a readout section for reading out the signal charge produced by said photoelectric conversion element at a predetermined readout timing are provided in a well region formed on a semiconductor substrate, comprising

said method comprising the steps of:

- converting light to a signal charge,
- storing said signal charge during a charge storage period, and
- a step of applying a substrate bias voltage to said well region and changing the substrate bias voltage during a said storage period of the signal charge by said photoelectric conversion element.

26. (Currently Amended) The driving method for a complementary metal-oxide  
semiconductor type solid-state image pickup device according to claim 25, wherein said  
photoelectric conversion element is provided for each of a plurality of pixels formed in a two-  
dimensional array on said semiconductor substrate.